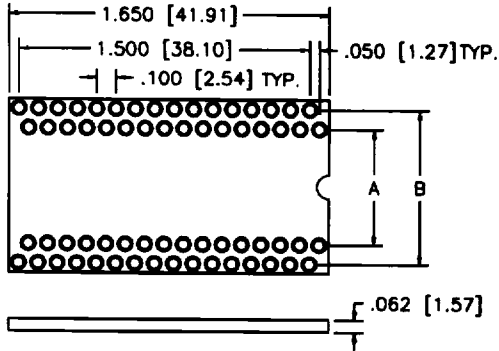


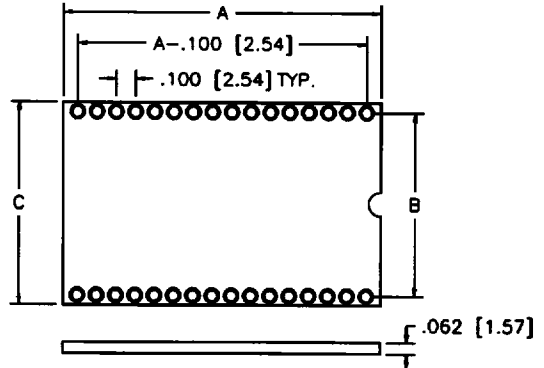
SERIES 401 QUAD SOCKET (LAMINATE WAFER)

SERIES 402 DIP SOCKET (LAMINATE WAFER)

SERIES 401 QUAD SOCKET



SERIES 402 DUAL IN-LINE



P/N	PINS	A	B	
401-764-	64	.750 [19.05]	.950 [24.15]	FOR ROCKWELL & NEC CHIP
401-864-	64	.600 [15.24]	.800 [20.32]	FOR FUJITSU CHIP

PIN	DIM "A"	DIM "B"	DIM "C"	
6	.300 [7.62]			306
8	.400 [10.16]			308
10	.500 [12.70]			310
14	.700 [17.78]			314
16	.800 [20.32]			316
18	.900 [22.86]			318
20	1.000 [25.40]			320
22	1.100 [27.94]			322
24	1.200 [30.48]			324
28	1.400 [35.56]			328
24	1.200 [30.48]			624
28	1.400 [35.56]			628
30	1.500 [38.10]			630
32	1.600 [40.64]			632
36	1.800 [45.72]			636
40	2.000 [50.80]			640
48	2.400 [60.96]			648
24	1.200 [30.48]		1.000 [25.40]	924
28	1.400 [35.56]		1.000 [25.40]	928
32	1.650 [41.91]		1.000 [25.40]	932
50	2.500 [63.05]		1.000 [25.40]	950
52	2.600 [66.04]		1.000 [25.40]	952
64	3.250 [82.55]		1.000 [25.40]	964

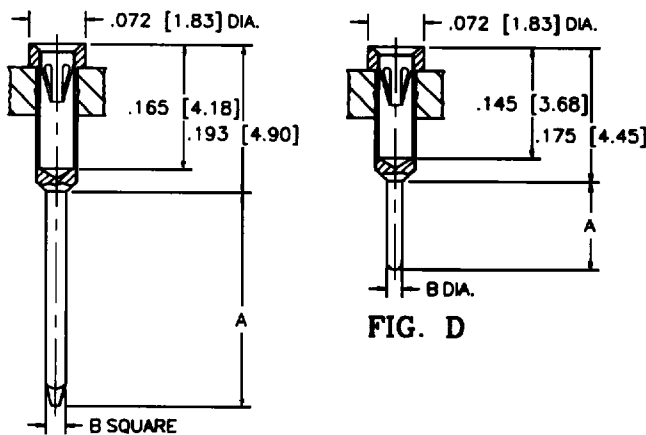


FIG. C

FIG. D

TERMINAL	FIG.	DIM "A"	DIM "B"
-01	D	.115 [2.92]	.020 [0.51]
-03	C	.510 [12.95]	.025 [0.64]
-08	D	.170 [4.31]	.020 [0.51]
-09	D	.280 [7.11]	.020 [0.51]
-94	D	.125 [3.17]	.018 [0.46]

CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.8 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL
 INSULATOR FR-4 EPOXY (LAMINATE)
 UL 94V-0 LISTED
TERMINAL CONTACT
 BRASS PER ASTM-B16
 BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +140°C

CONTACT FORCES
 INSERTION STANDARD 9 oz. AVG.
 WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

